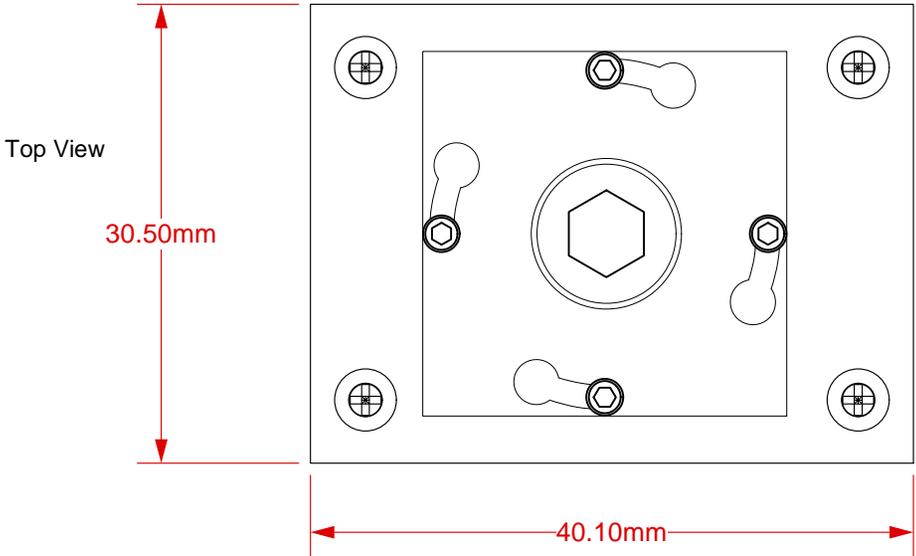


GHz BGA Socket - Direct mount, solderless

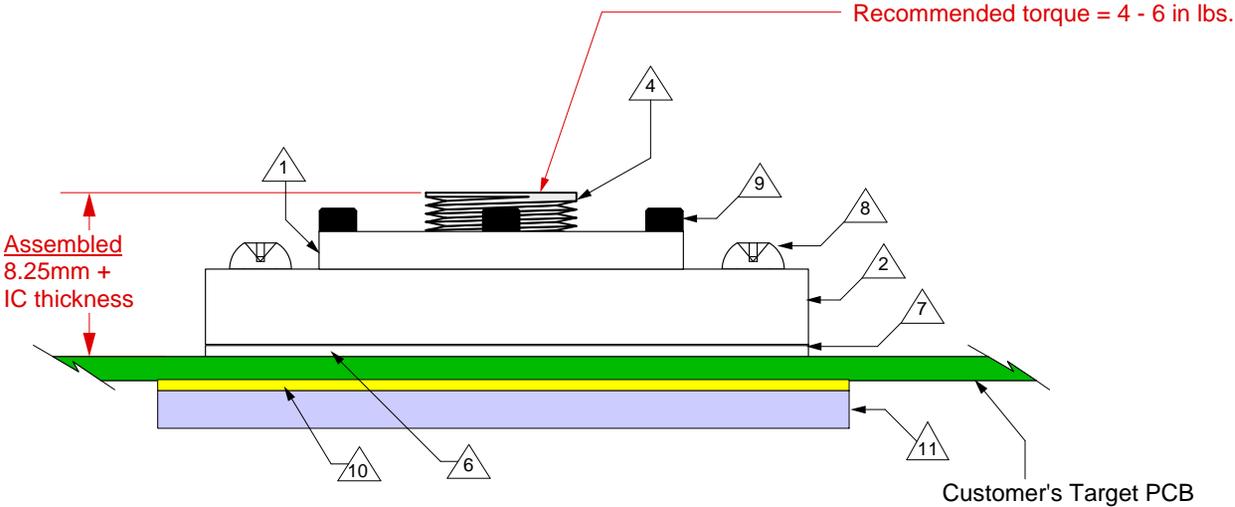
Features

- Directly mounts to target PCB (needs tooling holes) with hardware.
- High speed, reliable Elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly
- Ball guide prevents over compression of elastomer
- Easily removable swivel socket lid



Top View

Side View

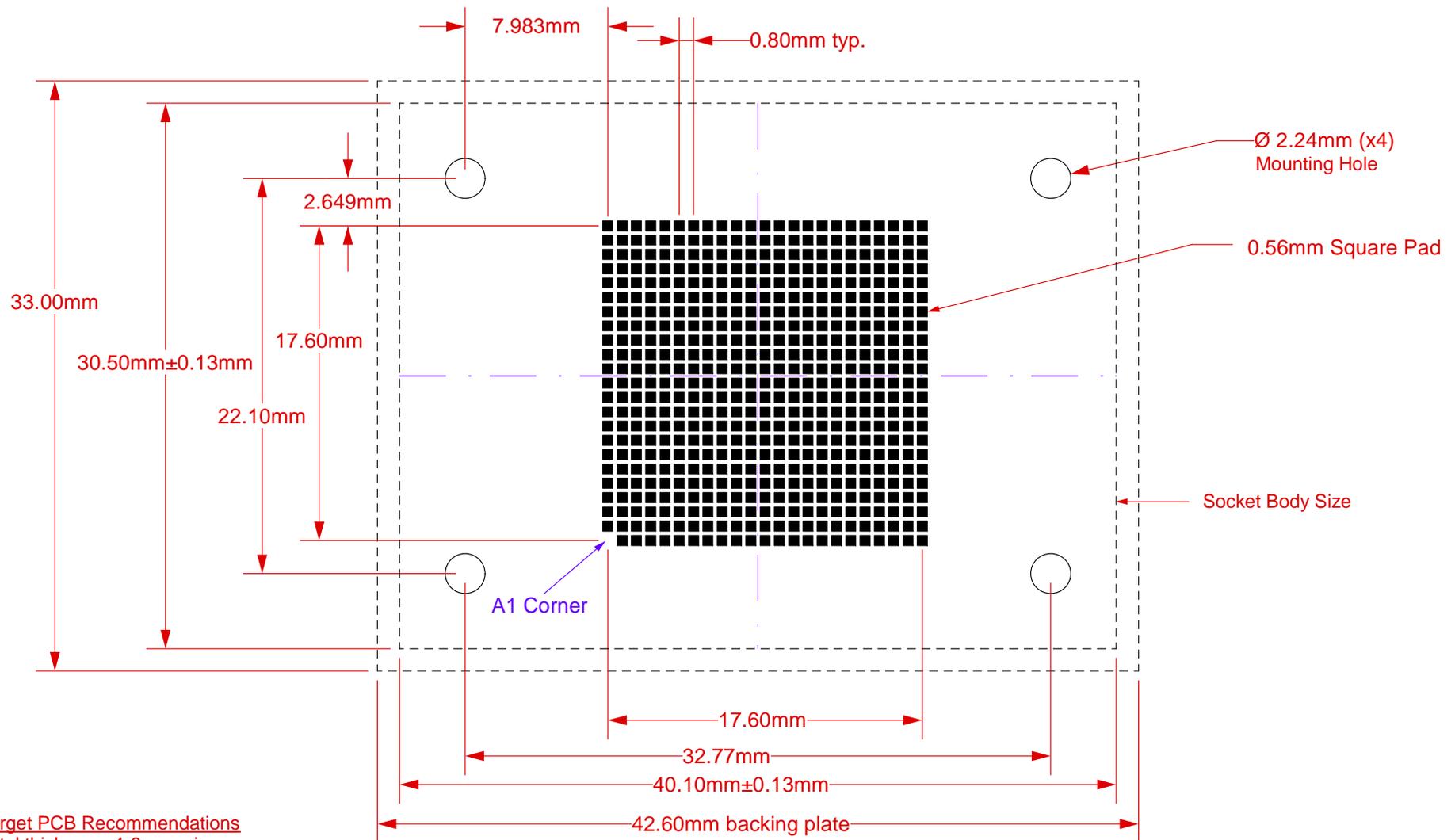


- 1 Socket Lid: Black anodized Aluminum. Thickness = 2.5mm.
- 2 Socket base: Black anodized Aluminum. Thickness = 5mm.
- 3 Compression Plate: Black anodized Aluminum. Thickness = 2.5mm.
- 4 Compression screw: Black anodized Aluminum. Thickness = 5mm, Hex socket = 5mm.
- 5 Elastomer: 40 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle). Thickness = 0.75mm.
- 6 Elastomer Guide: Non-clad FR4. Thickness = 0.725mm.
- 7 Ball Guide: Kapton polyimide.
- 8 Socket base screw: Philips round head, alloy steel with black oxide finish, 2-56 fine thread, 12.7mm long.
- 9 Socket lid screw: Shoulder screw, 18-8 SS, 0-80 fine thread.
- 10 Insulation Plate: FR4/G10, 1.59mm thick.
- 11 Backing Plate: Anodized Aluminum 6.35mm thick.

	SG-BGA-6055 Drawing	Status: Released	Scale: 2:1	Rev: D
	© 2009 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: H. Hansen		Date: 8/1/02
		File: SG-BGA-6055 Dwg.mcd	Modified: 8/3/09, AE	

All tolerances: ±0.125mm (unless stated otherwise). Materials and specifications are subject to change without notice.

Recommended PCB Layout
Top View



Target PCB Recommendations

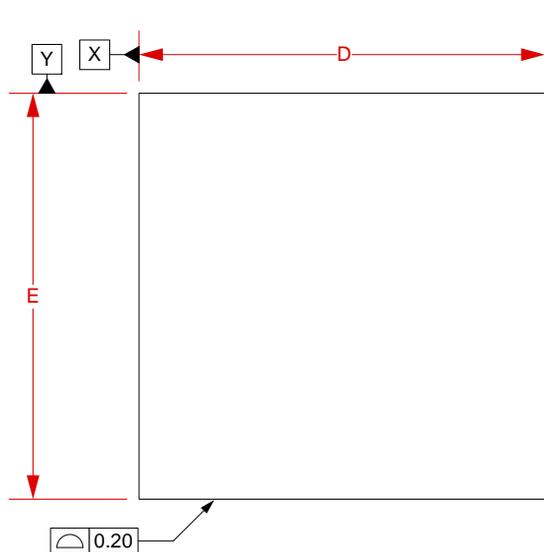
Total thickness: 1.6mm min.
 Plating: Gold or Solder finish
 PCB Pad height: Same or higher than solder mask

NOTE: Steel backing plate may be required based on end user's application

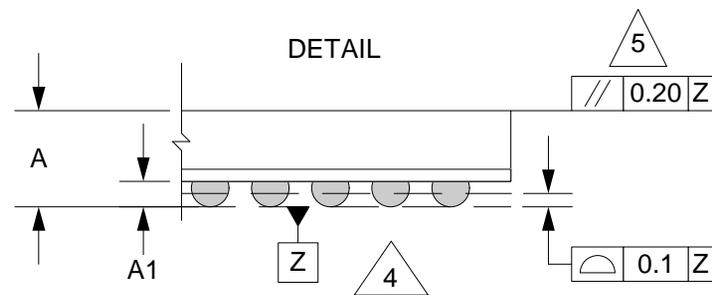
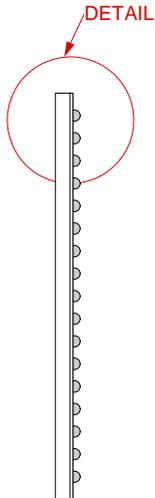
Recommended PCB Layout Tolerances: ±0.025mm [±0.001"] unless stated otherwise.

 <p>© 2009 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com</p>	SG-BGA-6055 Drawing		Status: Released	Scale: 2:1	Rev: D
	Drawing: H. Hansen			Date: 8/1/02	
	File: SG-BGA-6055 Dwg.mcd			Modified: 8/3/09, AE	

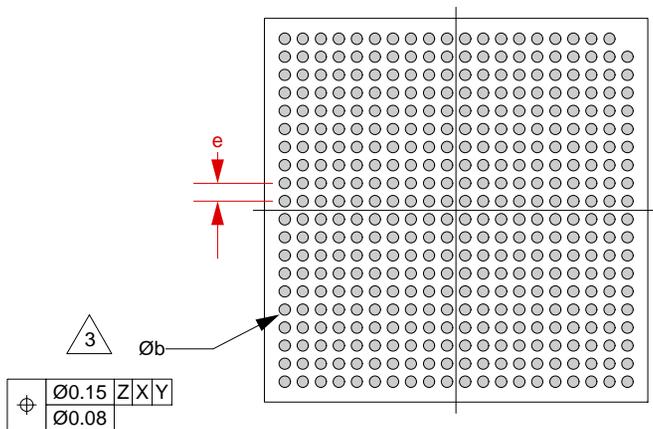
TOP VIEW
(reference only)



SIDE VIEW
(reference only)



BOTTOM VIEW
(reference only)



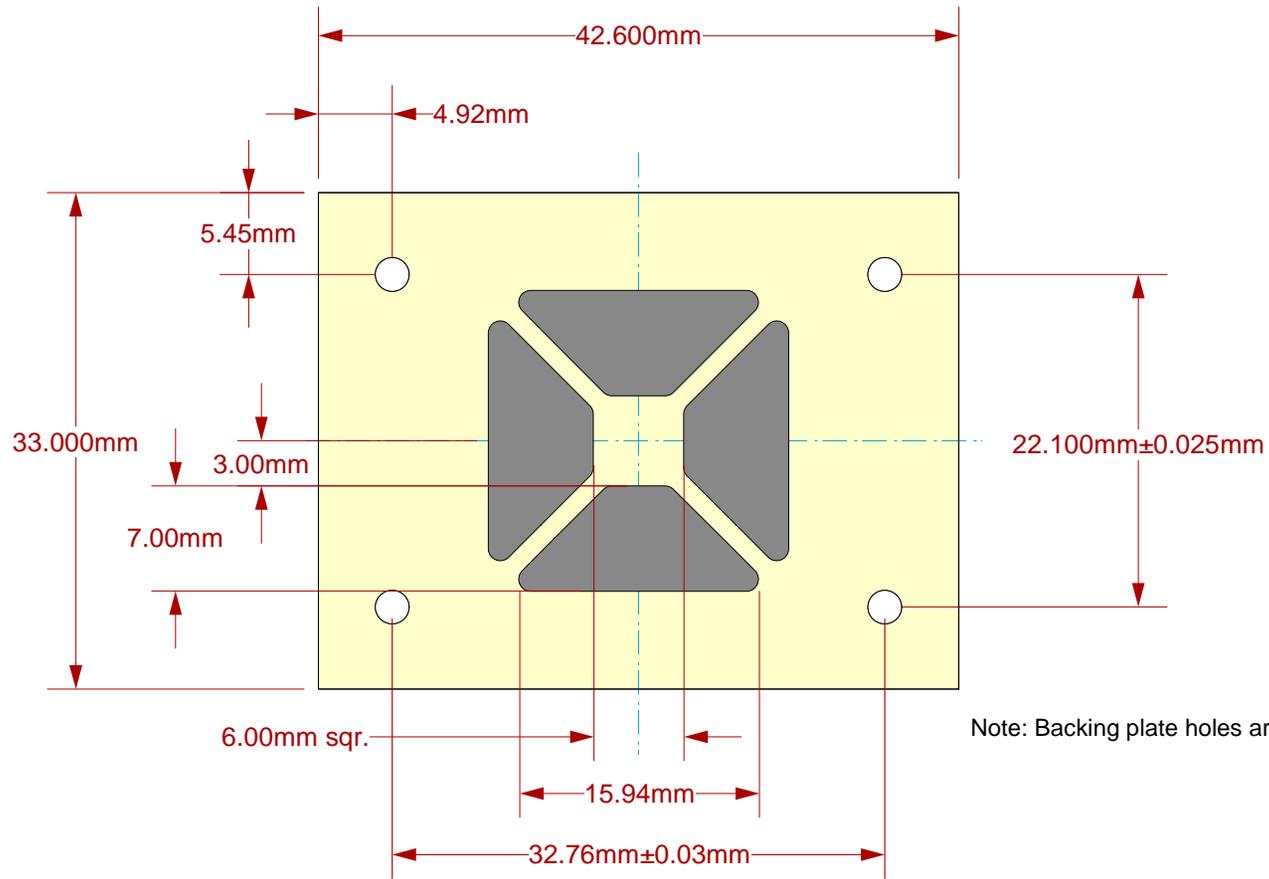
1. Dimensions are in millimeters.
 2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
- 3. Dimension b is measured at the maximum solder ball diameter, parallel to datum Z.
 - 4. Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
 - 5. Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		1.45
A1	0.25	0.35
b		0.45
D	19.00 BSC	
E	19.00 BSC	
e	0.8 BSC	

Array (23x23)-1= 528 Balls

	SG-BGA-6055 Drawing	Status: Released	Scale: -	Rev: D
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Top View



Side View



	SG-BGA-6055 Drawing	Status: Released	Scale: 2:1	Rev: D
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		File: SG-BGA-6055 Dwg.mcd	Modified: 8/3/09, AE	

All tolerances: ±0.125mm (unless stated otherwise). Materials and specifications are subject to change without notice.